



Integrated  
Circuit  
Systems, Inc.

**PRELIMINARY**

**ICS843034**  
FEMTOCLOCKS™

**MULTI-RATE 3.3V, 2.5V LVPECL FREQUENCY SYNTHESIZER**

## GENERAL DESCRIPTION



The ICS843034 is a general purpose, low phase noise LVPECL synthesizer which can generate frequencies for a wide variety of applications. The ICS843034 has a 4:1 input Multiplexer from which the following inputs can be selected: 1 differential input, 1 single-ended input, or two crystal oscillators, thus making the device ideal for frequency translation or frequency generation. Each differential LVPECL output pair has an output divider which can be independently set so that two different frequencies can be generated. Additionally, each LVPECL output pair has a dedicated power supply pin so the outputs can run at 3.3V or 2.5V. The ICS843034 also supplies a buffered copy of the reference clock or crystal frequency on the single-ended REF\_CLK pin which can be enabled or disabled (disabled by default). The output frequency can be programmed using either a serial or parallel programming interface.

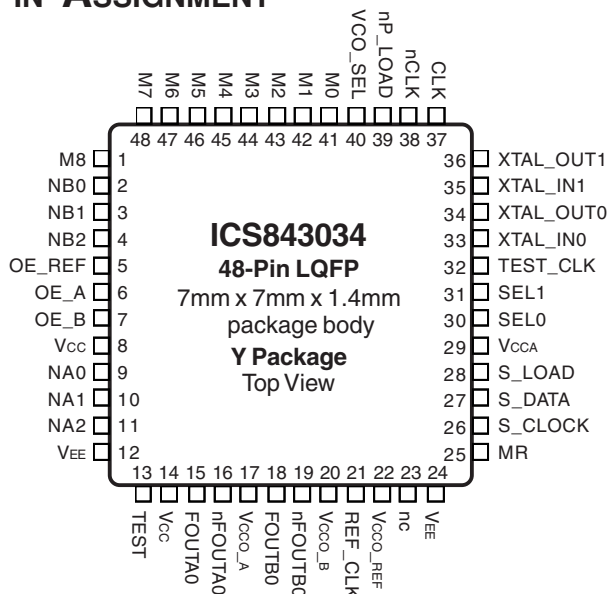
The phase jitter of the ICS843034 is less than 1ps rms, making it suitable for use in Fibre Channel, SONET, and Ethernet applications.

Example applications include systems which must support both FEC and non FEC rates. In 10Gb Fibre Channel, for example, you can use a 25.5MHz crystal to generate a 159.375MHz reference clock, and then switch to a 20.544MHz crystal to generate 164.355MHz for 66/64 FEC. Other applications could include supporting both Ethernet frequencies and SONET frequencies in an application. When Ethernet frequencies are needed, a 25MHz crystal can be used and when SONET frequencies are needed, the input MUX can be switched to select a 38.88MHz Crystal.

## FEATURES

- Dual differential 3.3V LVPECL outputs which can be set independently for either 3.3V or 2.5V
- 4:1 Input Mux:
  - 1 differential input
  - 1 single-ended input
  - 2 crystal oscillator interfaces
- CLK, nCLK pair can accept the following differential input levels: LVPECL, LVDS, LVHSTL, HCSL, SSTL
- TEST\_CLK accepts LVCMOS or LVTTTL input levels
- Output frequency range: 35MHz to 750MHz
- Crystal input frequency range: 12MHz to 40MHz
- VCO range: 560MHz to 750MHz
- Parallel or serial interface for programming feedback divider and output dividers
- RMS phase jitter at 333.33MHz, using a 22.222MHz crystal (12kHz to 20MHz): 0.80ps (typical)
- Supply voltage modes:
  - LVPECL outputs (core/outputs): 3.3V/3.3V, 3.3V/2.5V
  - REF\_CLK output (core/outputs): 3.3V/3.3V
- 0°C to 70°C ambient operating temperature
- Industrial temperature available upon request

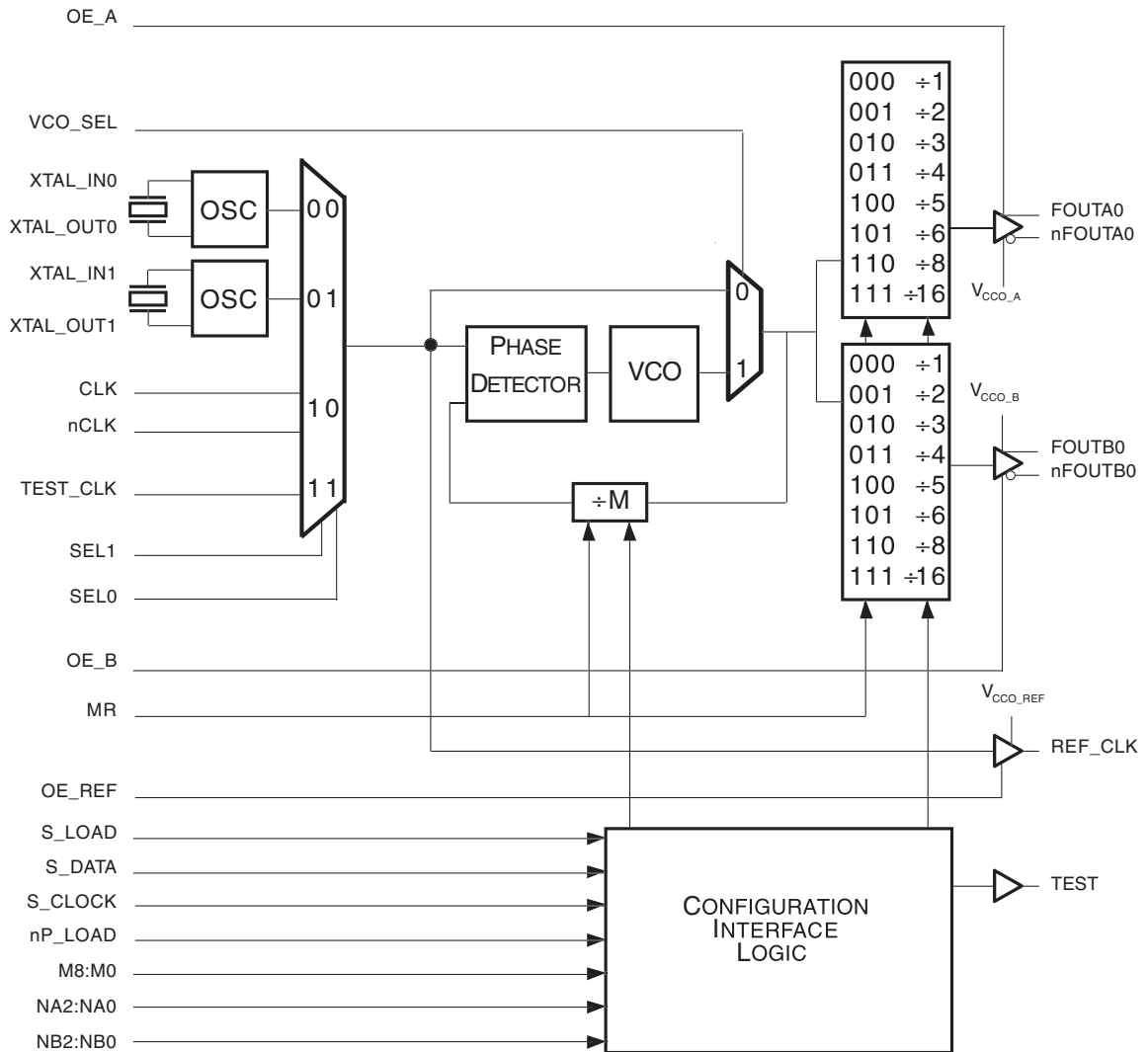
## PIN ASSIGNMENT



The Preliminary Information presented herein represents a product in prototyping or pre-production. The noted characteristics are based on initial product characterization. Integrated Circuit Systems, Incorporated (ICS) reserves the right to change any circuitry or specifications without notice.



**BLOCK DIAGRAM**





**FUNCTIONAL DESCRIPTION**

*NOTE: The functional description that follows describes operation using a 25MHz crystal. Valid PLL loop divider values for different crystal or input frequencies are defined in the Input Frequency Characteristics, Table 5, NOTE 1.*

The ICS843034 features a fully integrated PLL and therefore requires no external components for setting the loop bandwidth. A fundamental crystal is used as the input to the on-chip oscillator. The output of the oscillator is fed into the phase detector. A 25MHz crystal provides a 25MHz phase detector reference frequency. The VCO of the PLL operates over a range of 560MHz to 750MHz. The output of the M divider is also applied to the phase detector.

The phase detector and the M divider force the VCO output frequency to be M times the reference frequency by adjusting the VCO control voltage. Note that for some values of M (either too high or too low), the PLL will not achieve lock. The output of the VCO is scaled by a divider prior to being sent to each of the LVPECL output buffers. The divider provides a 50% output duty cycle.

The ICS843034 supports either serial or parallel programming modes to program the M feedback divider and N output divider. *Figure 1* shows the timing diagram for each mode. In parallel mode, the nP\_LOAD input is initially LOW. The data on the M, NA, and NB inputs are passed directly to the M divider and both N output dividers. On the LOW-to-HIGH transition of the nP\_LOAD input, the data is latched and the M and N dividers remain loaded until the next LOW transition on nP\_LOAD or until a serial event occurs. As a result, the M and Nx bits can be hardwired to set the M divider and Nx output divider to a specific default state that will automatically occur during power-up.

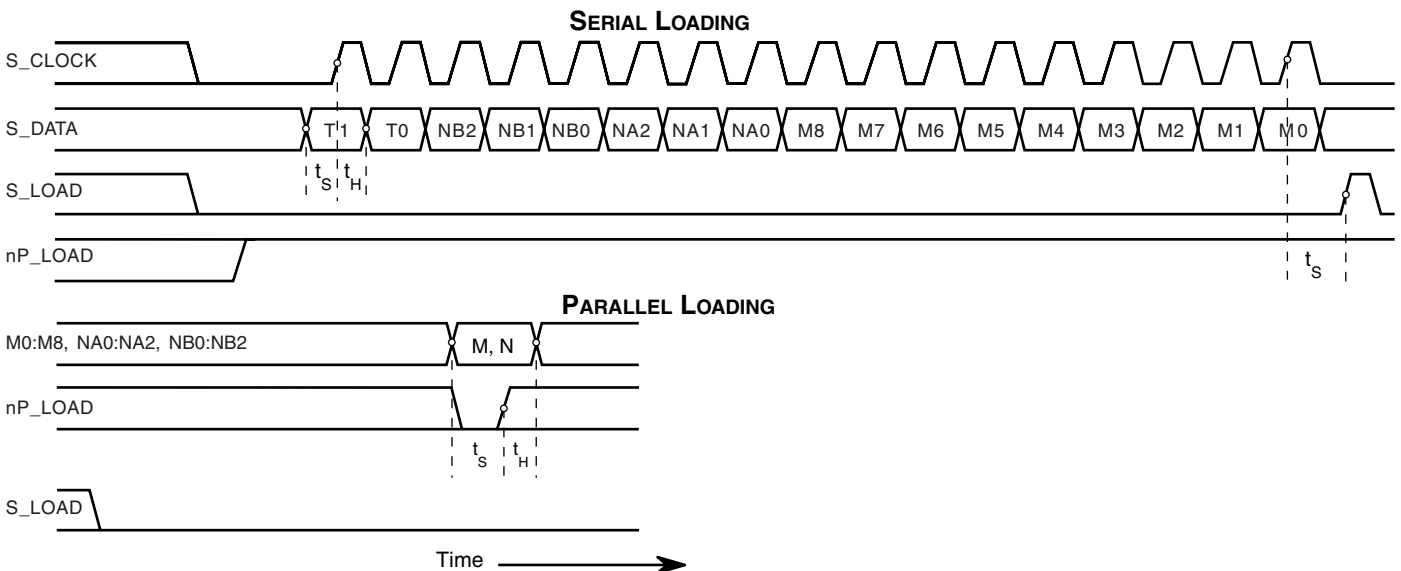
The TEST output is LOW when operating in the parallel input mode. The relationship between the VCO frequency, the crystal frequency and the M divider is defined as follows:

$$f_{VCO} = f_{xtal} \times M$$

The M value and the required values of M0 through M8 are shown in Table 3B to program the VCO Frequency Function Table. Valid M values for which the PLL will achieve lock for a 25MHz reference are defined as  $23 \leq M \leq 30$ . The frequency out is defined as follows:  $f_{OUT} = \frac{f_{VCO}}{N} = \frac{f_{xtal} \times M}{N}$

Serial operation occurs when nP\_LOAD is HIGH and S\_LOAD is LOW. The shift register is loaded by sampling the S\_DATA bits with the rising edge of S\_CLOCK. The contents of the shift register are loaded into the M divider and Nx output divider when S\_LOAD transitions from LOW-to-HIGH. The M divide and Nx output divide values are latched on the HIGH-to-LOW transition of S\_LOAD. If S\_LOAD is held HIGH, data at the S\_DATA input is passed directly to the M divider and Nx output divider on each rising edge of S\_CLOCK. The serial mode can be used to program the M and Nx bits and test bits T1 and T0. The internal registers T0 and T1 determine the state of the TEST output as follows:

T1	T0	TEST Output
0	0	LOW
0	1	S_Data, Shift Register Output
1	0	Output of M divider
1	1	FOUTA0 same frequency



**FIGURE 1. PARALLEL & SERIAL LOAD OPERATIONS**



**TABLE 1. PIN DESCRIPTIONS**

Number	Name	Type		Description
1, 41, 42, 43, 44, 45, 47, 48	M8, M0, M1, M2, M3, M4, M6, M7	Input	Pulldown	M divider input. Data latched on LOW-to-HIGH transition of nP_LOAD input. LVCMOS/LVTTL interface levels.
2, 3	NB0, NB1	Input	Pullup	Determines output divider value as defined in Table 3C, Function Table. LVCMOS/LVTTL interface levels.
4	NB2	Input	Pulldown	
5	OE_REF	Input	Pulldown	Output enable. Controls enabling and disabling of REF_CLK output. LVCMOS/LVTTL interface levels.
6	OE_A	Input	Pullup	Output enable. Controls enabling and disabling of FOUTA0, nFOUTA0 outputs. LVCMOS/LVTTL interface levels.
7	OE_B	Input	Pullup	Output enable. Controls enabling and disabling of FOUTB0, nFOUTB0 outputs. LVCMOS/LVTTL interface levels.
8, 14	V <sub>CC</sub>	Power		Core supply pins.
9, 10	NA0, NA1	Input	Pullup	Determines output divider value as defined in Table 3C, Function Table. LVCMOS/LVTTL interface levels.
11	NA2	Input	Pulldown	
12, 24	V <sub>EE</sub>	Power		Negative supply pins.
13	TEST	Output		Test output which is ACTIVE in the serial mode of operation. Output driven LOW in parallel mode. LVCMOS/LVTTL interface levels.
15, 16	FOUTA0, nFOUTA0	Output		Differential output for the synthesizer. LVPECL interface levels.
17	V <sub>CCO_A</sub>	Power		Output supply pin for FOUTA0, nFOUTA0.
18, 19	FOUTB0, nFOUTB0	Output		Differential output for the synthesizer. LVPECL interface levels.
20	V <sub>CCO_B</sub>	Power		Output supply pin for FOUTB0, nFOUTB0.
21	REF_CLK	Output		Reference clock output. LVCMOS/LVTTL interface levels.
22	V <sub>CCO_REF</sub>	Power		Output supply pin for REF_CLK.
23	nc	Unused		No connect.
25	MR	Input	Pulldown	Active High Master Reset. When logic HIGH, forces the internal dividers are reset causing the true outputs FOUTx to go low and the inverted outputs nFOUTx to go high. When logic LOW, the internal dividers and the outputs are enabled. Assertion of MR does not affect loaded M, N, and T values. LVCMOS/LVTTL interface levels.
26	S_CLOCK	Input	Pulldown	Clocks in serial data present at S_DATA input into the shift register on the rising edge of S_CLOCK. LVCMOS/LVTTL interface levels.
27	S_DATA	Input	Pulldown	Shift register serial input. Data sampled on the rising edge of S_CLOCK. LVCMOS/LVTTL interface levels.
28	S_LOAD	Input	Pulldown	Controls transition of data from shift register into the dividers. LVCMOS/LVTTL interface levels.
29	V <sub>CCA</sub>	Power		Analog supply pin.
30, 31	SEL0, SEL1	Input	Pulldown	Clock select inputs. LVCMOS/LVTTL interface levels.
32	TEST_CLK	Input	Pulldown	Test clock input. LVCMOS/LVTTL interface levels.
33, 34	XTAL_IN0, XTAL_OUT0	Input		Crystal oscillator interface. XTAL_IN0 is the input, XTAL_OUT0 is the output.
35, 36	XTAL_IN1, XTAL_OUT1	Input		Crystal oscillator interface. XTAL_IN1 is the input, XTAL_OUT1 is the output.

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Number	Name	Type		Description
37	CLK	Input	Pulldown	Non-inverting differential clock input.
38	nCLK	Input	Pullup/ Pulldown	Inverting differential clock input. $V_{CC}/2$ default when left floating.
39	nP_LOAD	Input	Pulldown	Parallel load input. Determines when data present at M8:M0 is loaded into M divider, and when data present at NA2:NA0 and NB2:NB0 is loaded into the N output dividers. LVCMOS/LVTTL interface levels.
40	VCO_SEL	Input	Pullup	Determines whether synthesizer is in PLL or bypass mode. LVCMOS/LVTTL interface levels.
46	M5	Input	Pullup	M divider inputs. Data latched on LOW-to-HIGH transition of nP_LOAD input. LVCMOS/LVTTL interface levels.

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

**TABLE 2. PIN CHARACTERISTICS**

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
$C_{IN}$	Input Capacitance				4		pF
$C_{PD}$	Power Dissipation Capacitance	REF_CLK	$V_{CC}, V_{CCA}, V_{CCO\_REF} = 3.465V$		TBD		pF
$R_{PULLUP}$	Input Pullup Resistor				51		k $\Omega$
$R_{PULLDOWN}$	Input Pulldown Resistor				51		k $\Omega$
$R_{OUT}$	Output Impedance	REF_CLK		5	7	12	$\Omega$



**TABLE 3A. PARALLEL AND SERIAL MODE FUNCTION TABLE**

Inputs							Conditions
MR	nP_LOAD	M	N	S_LOAD	S_CLOCK	S_DATA	
H	X	X	X	X	X	X	Reset. Forces outputs LOW.
L	L	Data	Data	X	X	X	Data on M and N inputs passed directly to the M divider and N output divider. TEST output forced LOW.
L	↑	Data	Data	L	X	X	Data is latched into input registers and remains loaded until next LOW transition or until a serial event occurs.
L	H	X	X	L	↑	Data	Serial input mode. Shift register is loaded with data on S_DATA on each rising edge of S_CLOCK.
L	H	X	X	↑	L	Data	Contents of the shift register are passed to the M divider and N output divider.
L	H	X	X	↓	L	Data	M divider and N output divider values are latched.
L	H	X	X	L	X	X	Parallel or serial input do not affect shift registers.
L	H	X	X	H	↑	Data	S_DATA passed directly to M divider as it is clocked.

NOTE: L = LOW  
 H = HIGH  
 X = Don't care  
 ↑ = Rising edge transition  
 ↓ = Falling edge transition

**TABLE 3B. PROGRAMMABLE VCO FREQUENCY FUNCTION TABLE**

VCO Frequency (MHz)	M Divide	256	128	64	32	16	8	4	2	1
		M8	M7	M6	M5	M4	M3	M2	M1	M0
575	23	0	0	0	0	1	0	1	1	1
•	•	•	•	•	•	•	•	•	•	•
700	28	0	0	0	0	1	1	1	0	0
•	•	•	•	•	•	•	•	•	•	•
750	30	0	0	0	0	1	1	1	1	0

NOTE 1: These M divide values and the resulting frequencies correspond to crystal or TEST\_CLK input frequency of 25MHz.

**TABLE 3C. PROGRAMMABLE OUTPUT DIVIDER FUNCTION TABLE**

Inputs			N Divider Value	Output Frequency (MHz)	
*NX2	*NX1	*NX0		Minimum	Maximum
0	0	0	1	560	750
0	0	1	2	280	375
0	1	0	3	186.66	250
0	1	1	4	140	187.5
1	0	0	5	112	150
1	0	1	6	93.33	125
1	1	0	8	70	93.75
1	1	1	16	35	46.875

\*NOTE: X denotes Bank A or Bank B



**ABSOLUTE MAXIMUM RATINGS**

Supply Voltage, $V_{CC}$	4.6V
Inputs, $V_i$	-0.5V to $V_{CC} + 0.5V$
Outputs, $V_o$ (LVCMOS)	-0.5V to $V_{CCO} + 0.5V$
Outputs, $I_o$ (LVPECL)	
Continuous Current	50mA
Surge Current	100mA
Package Thermal Impedance, $\theta_{JA}$	47.9°C/W (0 lfpm)
Storage Temperature, $T_{STG}$	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

**TABLE 4A. POWER SUPPLY DC CHARACTERISTICS,  $V_{CC} = V_{CCA} = 3.3V \pm 5\%$ ,  $V_{CCO\_A} = V_{CCO\_B} = 3.3V \pm 5\%$  OR  $2.5V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{CC}$	Core Supply Voltage		3.135	3.3	3.465	V
$V_{CCA}$	Analog Supply Voltage		3.135	3.3	3.465	V
$V_{CCO\_A}$ $V_{CCO\_B}$	Output Supply Voltage		3.135	3.3	3.465	V
			2.375	2.5	2.625	V
$V_{CCO\_REF}$	Output Supply	REF_CLK	3.135	3.3	3.465	V
$I_{EE}$	Power Supply Current			185		mA
$I_{CCA}$	Analog Supply Current			20		mA



**TABLE 4B. LVC MOS/LVTTL DC CHARACTERISTICS,  $V_{CC} = V_{CCA} = 3.3V \pm 5\%$ ,  $V_{CCO\_A} = V_{CCO\_B} = V_{CCO\_REF} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  to  $70^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{IH}$	Input High Voltage		2		$V_{CC} + 0.3$	V
$V_{IM}$	Input Mid Voltage		$V_{CC}/2 - 0.2V$		$V_{CC}/2 + 0.2V$	V
$V_{IL}$	Input Low Voltage		-0.3		0.8	V
$I_{IH}$	Input High Current	TEST_CLK, MR, SEL[1:0], OE_REF, S_CLOCK, S_DATA, S_LOAD, nP_LOAD, Nx2, M1:M4, M6:M8	$V_{CC} = V_{IN} = 3.465V$		150	$\mu A$
		Nx0, Nx1, M5, OE_A, OE_B, VCO_SEL	$V_{CC} = V_{IN} = 3.465V$		5	$\mu A$
$I_{IL}$	Input Low Current	TEST_CLK, MR, SEL[1:0], OE_REF, S_CLOCK, S_DATA, S_LOAD, nP_LOAD, Nx2, M1:M4, M6:M8	$V_{CC} = 3.465V,$ $V_{IN} = 0V$	-5		$\mu A$
		Nx0, Nx1, M5, OE_A, OE_B, VCO_SEL	$V_{CC} = 3.465V,$ $V_{IN} = 0V$	-150		$\mu A$
$V_{OH}$	Output High Voltage	TEST; NOTE 1	$V_{CCO\_REF} = 3.3V \pm 5\%$	2.6		V
		REF_CLK		$V_{CCO\_REF} - 0.3V$	0.4	V
$V_{OL}$	Output Low Voltage	TEST; NOTE 1	$V_{CCO\_REF} = 3.3V \pm 5\%$		0.5	V

NOTE 1: Output terminated with  $50\Omega$  to  $V_{CCO\_REF}/2$ .





**TABLE 4C. DIFFERENTIAL DC CHARACTERISTICS,  $V_{CC} = V_{CCA} = 3.3V \pm 5\%$ ,  $V_{CCO,A} = V_{CCO,B} = 3.3V \pm 5\%$  OR  $2.5V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$I_{IH}$	Input High Current	nCLK	$V_{IN} = V_{CC} = 3.465V$		150	$\mu A$
		CLK	$V_{IN} = V_{CC} = 3.465V$		150	$\mu A$
$I_{IL}$	Input Low Current	nCLK	$V_{IN} = 0V, V_{CC} = 3.465V$	-150		$\mu A$
		CLK	$V_{IN} = 0V, V_{CC} = 3.465V$	-5		$\mu A$
$V_{PP}$	Peak-to-Peak Input Voltage		0.15		1.3	V
$V_{CMR}$	Common Mode Input Voltage; NOTE 1, 2		$V_{EE} + 0.5$		$V_{CC} - 0.85$	V

NOTE 1: For single ended applications, the maximum input voltage for CLK, nCLK is  $V_{CC} + 0.3V$ .

NOTE 2: Common mode voltage is defined as  $V_{IH}$ .

**TABLE 4D. LVPECL DC CHARACTERISTICS,  $V_{CC} = V_{CCA} = 3.3V \pm 5\%$ ,  $V_{CCO,A} = V_{CCO,B} = 3.3V \pm 5\%$  OR  $2.5V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{OH}$	Output High Voltage; NOTE 1		$V_{CCO} - 1.4$		$V_{CCO} - 0.9$	V
$V_{OL}$	Output Low Voltage; NOTE 1		$V_{CCO} - 2.0$		$V_{CCO} - 1.7$	V
$V_{SWING}$	Peak-to-Peak Output Voltage Swing		0.6		1.0	V

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{CCO,A}, V_{CCO,B} - 2V$ .

**TABLE 5. INPUT FREQUENCY CHARACTERISTICS,  $V_{CC} = V_{CCA} = 3.3V \pm 5\%$ ,  $V_{CCO,A} = V_{CCO,B} = 3.3V \pm 5\%$  OR  $2.5V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$f_{IN}$	Input Frequency	XTAL_IN0/XTAL_OUT0, XTAL_IN1/XTAL_OUT1	12		40	MHz
		CLK/nCLK, TEST_CLK	12		TBD	MHz
		S_CLOCK			50	MHz
$t_R/t_F$	Input Rise/Fall Time	TEST_CLK		TBD		ns
		S_LOAD, S_DATA, S_CLOCK		TBD		ns

NOTE: For the input crystal, CLK/nCLK and TEST\_CLK frequency range, the M value must be set for the VCO to operate within the 560MHz to 750MHz range. Using the minimum input frequency of 12MHz, valid values of M are  $47 \leq M \leq 62$ . Using the maximum frequency of 40MHz, valid values of M are  $14 \leq M \leq 18$ .

**TABLE 6. CRYSTAL CHARACTERISTICS**

Parameter	Test Conditions	Minimum	Typical	Maximum	Units
Mode of Oscillation		Fundamental			
Frequency		12		40	MHz
Equivalent Series Resistance (ESR)				50	$\Omega$
Shunt Capacitance				7	pF
Drive Level				1	mW



**TABLE 7A. AC CHARACTERISTICS,  $V_{CC} = V_{CCA} = V_{CCO\_A} = V_{CCO\_B} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$F_{OUT}$	Output Frequency		35		750	MHz
$f_{jit}(\emptyset)$	Phase Jitter, RMS (Random); NOTE 1, 2	333.33MHz, Integration Range: 12kHz - 20MHz		0.80		ps
$f_{jit}(cc)$	Cycle-to-Cycle Jitter; NOTE 3, 4			TBD		ps
$t_{sk}(o)$	Output Skew; NOTE 2, 4, 5	Measured @ the same Output Frequency		50		ps
$t_R / t_F$	Output Rise/Fall Time	LVPECL Outputs	20% to 80%	200	700	ps
		REF_CLK				
$t_S$	Setup Time	M, N to nP_LOAD	5			ns
		S_DATA to S_CLOCK	5			ns
		S_CLOCK to S_LOAD	5			ns
$t_H$	Hold Time	M, N to nP_LOAD	5			ns
		S_DATA to S_CLOCK	5			ns
		S_CLOCK to S_LOAD	5			ns
odc	Output Duty Cycle			50		%
$t_{LOCK}$	PLL Lock Time				1	ms

See Parameter Measurement Information section.

NOTE 1: Please refer to the Phase Noise Plot.

NOTE 2: Characterized with REF\_CLK output disabled.

NOTE 3: Jitter performance using XTAL inputs.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 5: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at the output differential cross points.

**TABLE 7B. AC CHARACTERISTICS,  $V_{CC} = V_{CCA} = 3.3V \pm 5\%$ ,  $V_{CCO\_A} = V_{CCO\_B} = 2.5V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$F_{OUT}$	Output Frequency		35		750	MHz
$f_{jit}(\emptyset)$	Phase Jitter, RMS (Random); NOTE 1, 2	333.33MHz, Integration Range: 12kHz - 20MHz		TBD		ps
$f_{jit}(cc)$	Cycle-to-Cycle Jitter; NOTE 3, 4			TBD		ps
$t_{sk}(o)$	Output Skew; NOTE 2, 4, 5	Measured @ the same Output Frequency		50		ps
$t_R / t_F$	Output Rise/Fall Time	LVPECL Outputs	20% to 80%	200	700	ps
		REF_CLK				
$t_S$	Setup Time	M, N to nP_LOAD	5			ns
		S_DATA to S_CLOCK	5			ns
		S_CLOCK to S_LOAD	5			ns
$t_H$	Hold Time	M, N to nP_LOAD	5			ns
		S_DATA to S_CLOCK	5			ns
		S_CLOCK to S_LOAD	5			ns
odc	Output Duty Cycle			50		%
$t_{LOCK}$	PLL Lock Time				1	ms

For notes, see Table 7A above.



**MULTI-RATE 3.3V, 2.5V LVPECL FREQUENCY SYNTHESIZER**

**TABLE 7C. AC CHARACTERISTICS,  $V_{CC} = V_{CCA} = 3.3V \pm 5\%$ ,  $V_{CCO\_A} = 3.3V \pm 5\%$ ,  $V_{CCO\_B} = 2.5V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$  OR  $V_{CC} = V_{CCA} = 3.3V \pm 5\%$ ,  $V_{CCO\_A} = 2.5V \pm 5\%$ ,  $V_{CCO\_B} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$F_{OUT}$	Output Frequency		35		750	MHz
$f_{jit}(\emptyset)$	Phase Jitter, RMS (Random); NOTE 1, 2	333.33MHz, Integration Range: 12kHz - 20MHz		TBD		ps
$f_{jit}(cc)$	Cycle-to-Cycle Jitter; NOTE 3, 4			TBD		ps
$tsk(o)$	Output Skew; NOTE 2, 4, 5	Measured @ the same Output Frequency		50		ps
$t_R / t_F$	Output Rise/Fall Time	LVPECL Outputs				
		REF_CLK	20% to 80%	200	700	ps
$t_S$	Setup Time	M, N to nP_LOAD		5		ns
		S_DATA to S_CLOCK		5		ns
		S_CLOCK to S_LOAD		5		ns
$t_H$	Hold Time	M, N to nP_LOAD		5		ns
		S_DATA to S_CLOCK		5		ns
		S_CLOCK to S_LOAD		5		ns
odc	Output Duty Cycle			50		%
$t_{LOCK}$	PLL Lock Time				1	ms

See Parameter Measurement Information section.

NOTE 1: Please refer to the Phase Noise Plot.

NOTE 2: Characterized with REF\_CLK output disabled.

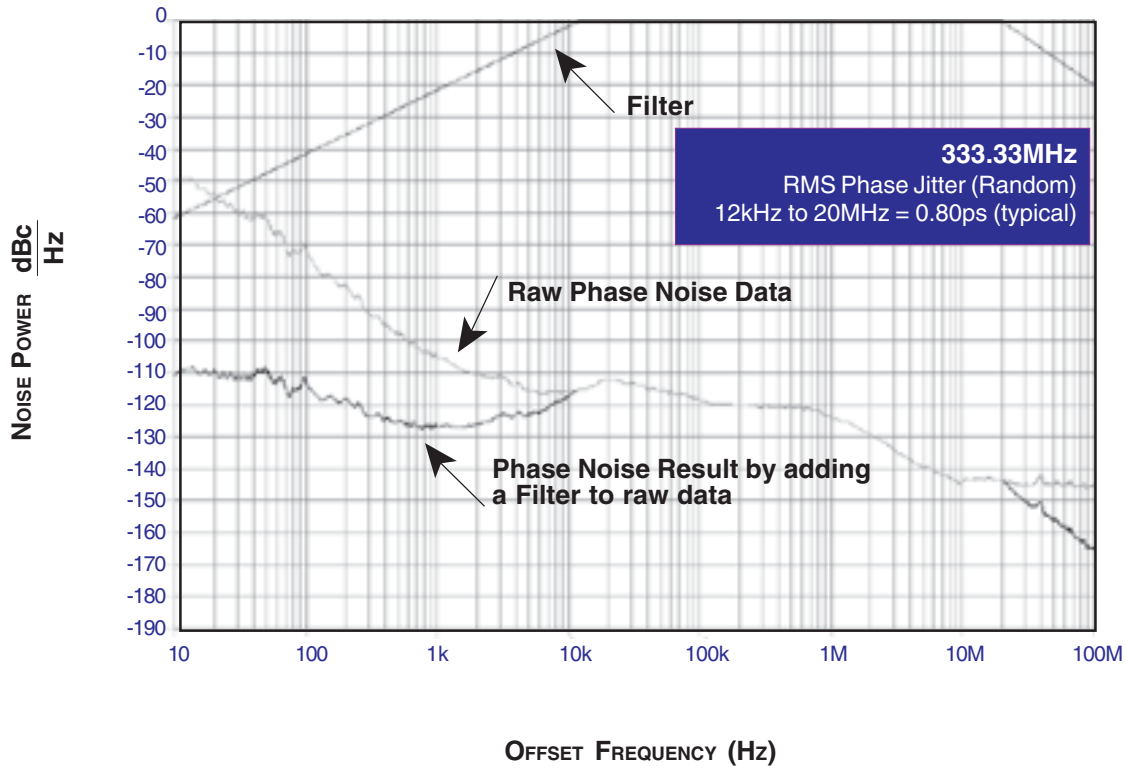
NOTE 3: Jitter performance using XTAL inputs.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 5: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at the output differential cross points.

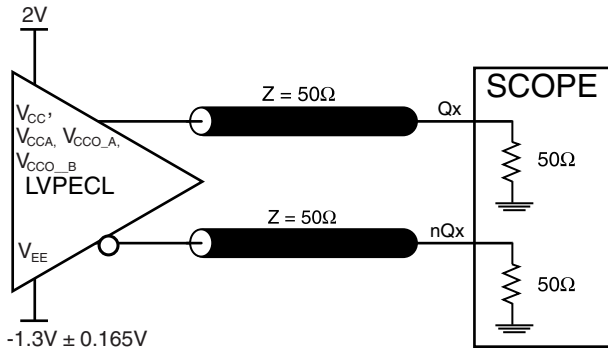


**TYPICAL PHASE NOISE AT 333.33MHz**

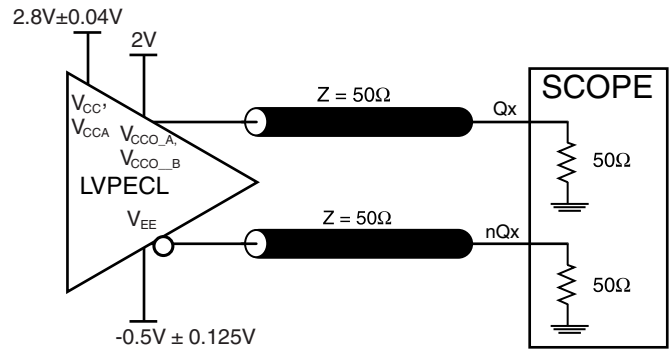




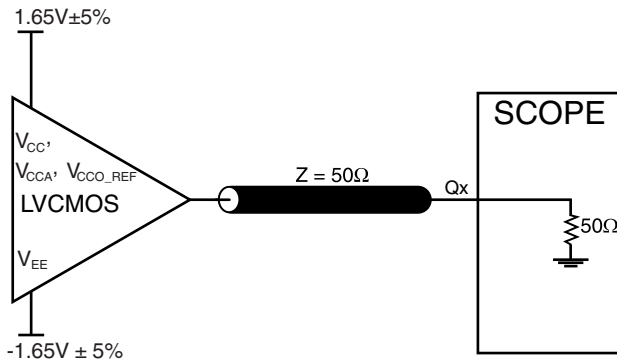
**PARAMETER MEASUREMENT INFORMATION**



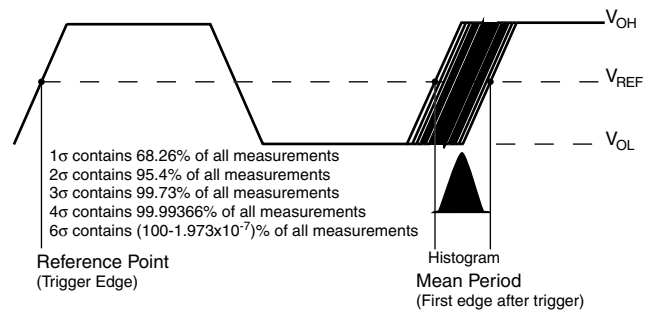
**3.3V CORE/3.3V OUTPUT LOAD AC TEST CIRCUIT**  
FOUTA0/nFOUTA0, FOUTB0/nFOUTB0



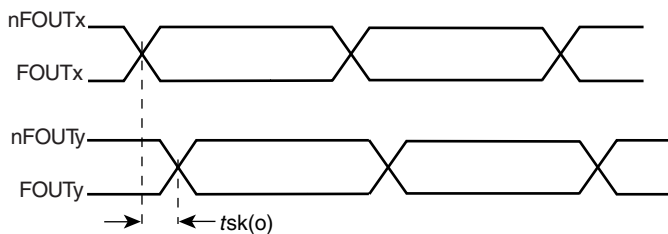
**3.3V CORE/2.5V OUTPUT LOAD AC TEST CIRCUIT**  
FOUTA0/nFOUTA0, FOUTB0/nFOUTB0



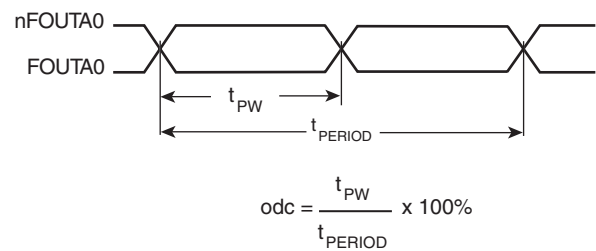
**3.3V CORE/3.3V REF\_CLK OUTPUT LOAD AC TEST CIRCUIT**



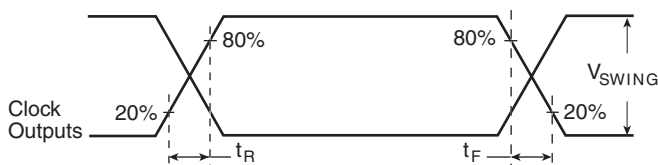
**PERIOD JITTER**



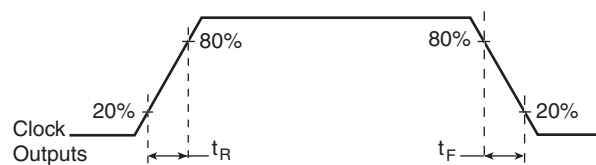
**OUTPUT SKEW**



**OUTPUT DUTY CYCLE/OUTPUT PULSE WIDTH/PERIOD**



**LVPECL OUTPUT RISE/FALL TIME**



**LVC MOS OUTPUT RISE/FALL TIME**



## APPLICATION INFORMATION

### POWER SUPPLY FILTERING TECHNIQUES

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. The ICS843034 provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL.  $V_{CC}$ ,  $V_{CCA}$ , and  $V_{CCO_x}$  should be individually connected to the power supply plane through vias, and bypass capacitors should be used for each pin. To achieve optimum jitter performance, power supply isolation is required. *Figure 2* illustrates how a  $10\Omega$  resistor along with a  $10\mu F$  and a  $.01\mu F$  bypass capacitor should be connected to each  $V_{CCA}$  pin.

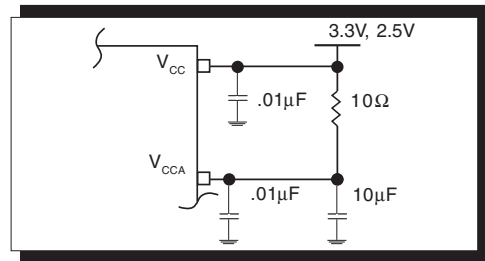


FIGURE 2. POWER SUPPLY FILTERING

### WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LVCMOS/LVTTL LEVELS

*Figure 3* shows how the differential input can be wired to accept single ended levels. The reference voltage  $V_{REF} = V_{CC}/2$  is generated by the bias resistors  $R1$ ,  $R2$  and  $C1$ . This bias circuit should be located as close as possible to the input pin. The ratio

of  $R1$  and  $R2$  might need to be adjusted to position the  $V_{REF}$  in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{CC} = 3.3V$ ,  $V_{REF}$  should be 1.25V and  $R2/R1 = 0.609$ .

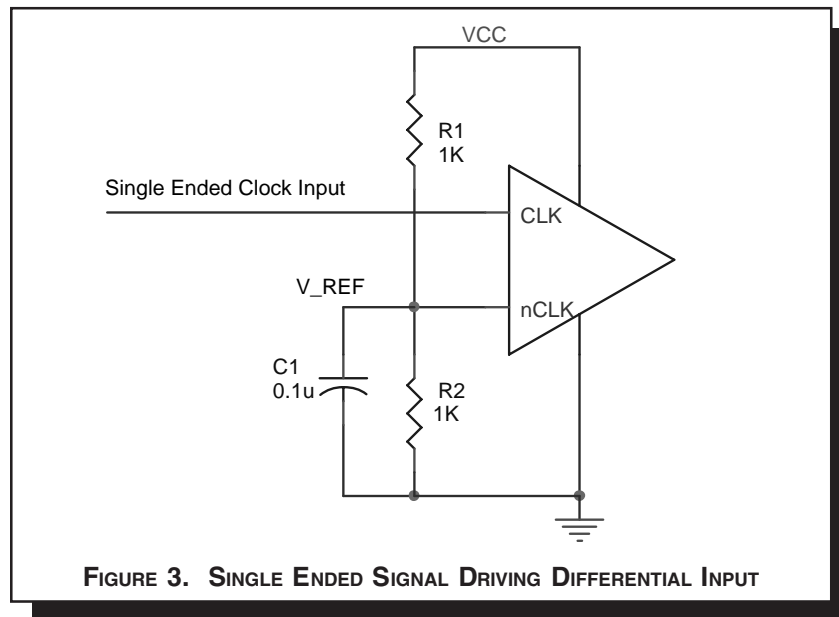


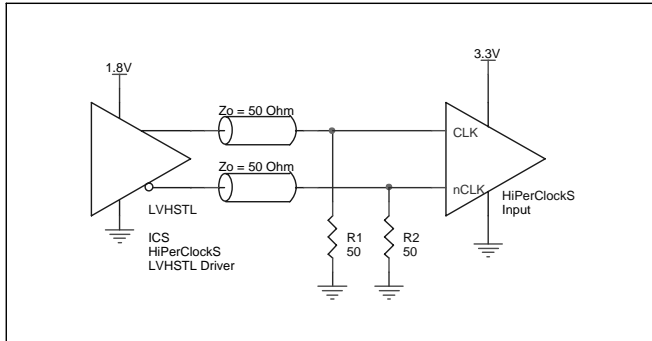
FIGURE 3. SINGLE ENDED SIGNAL DRIVING DIFFERENTIAL INPUT



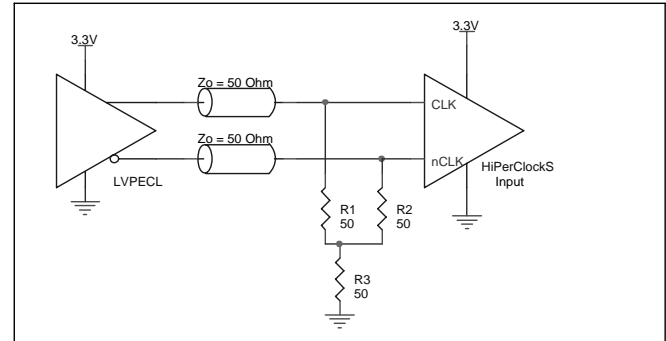
**DIFFERENTIAL CLOCK INPUT INTERFACE**

The CLK/nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSSL and other differential signals. Both  $V_{SWING}$  and  $V_{OH}$  must meet the  $V_{PP}$  and  $V_{CMR}$  input requirements. Figures 4A to 4D show interface examples for the HiPerClockS CLK/nCLK input driven by the most common driver types. The input interfaces suggested

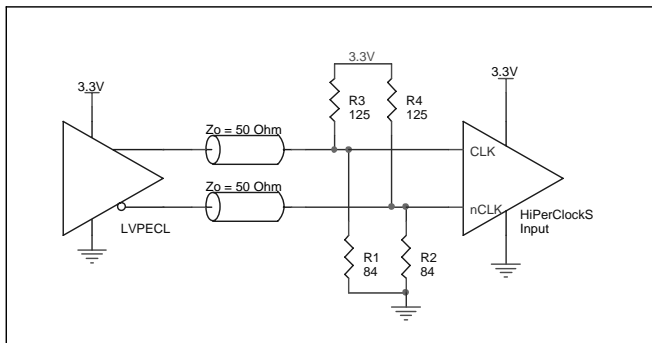
here are examples only. Please consult with the vendor of the driver component to confirm the driver termination requirements. For example in *Figure 4A*, the input termination applies for ICS HiPerClockS LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.



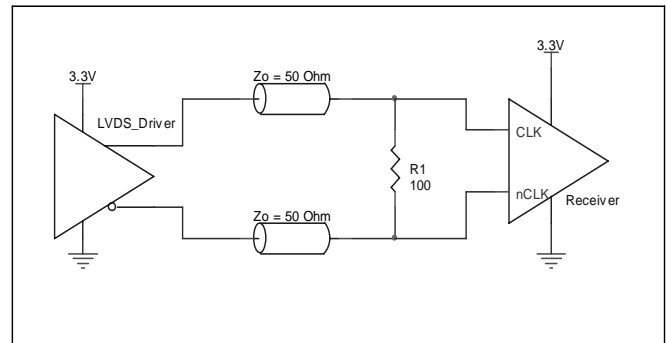
**FIGURE 4A. HiPerClockS CLK/nCLK INPUT DRIVEN BY ICS HiPerClockS LVHSTL DRIVER**



**FIGURE 4B. HiPerClockS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER**



**FIGURE 4C. HiPerClockS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER**



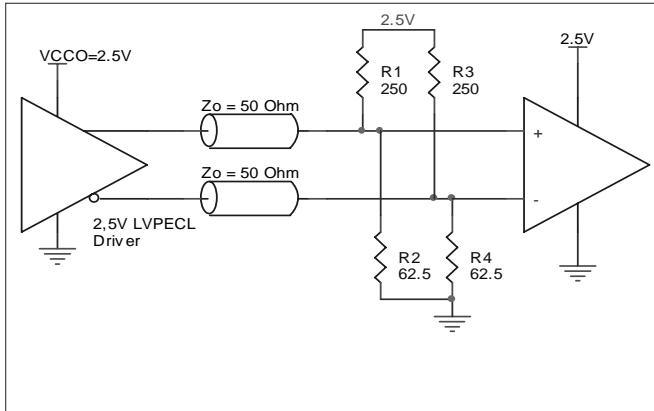
**FIGURE 4D. HiPerClockS CLK/nCLK INPUT DRIVEN BY 3.3V LVDS DRIVER**



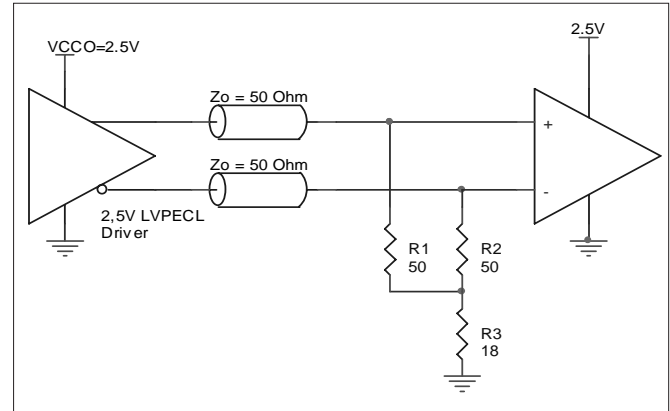
**TERMINATION FOR 2.5V LVPECL OUTPUT**

Figure 5A and Figure 5B show examples of termination for 2.5V LVPECL driver. These terminations are equivalent to terminating 50Ω to  $V_{CC} - 2V$ . For  $V_{CC} = 2.5V$ , the  $V_{CC} - 2V$  is very close to

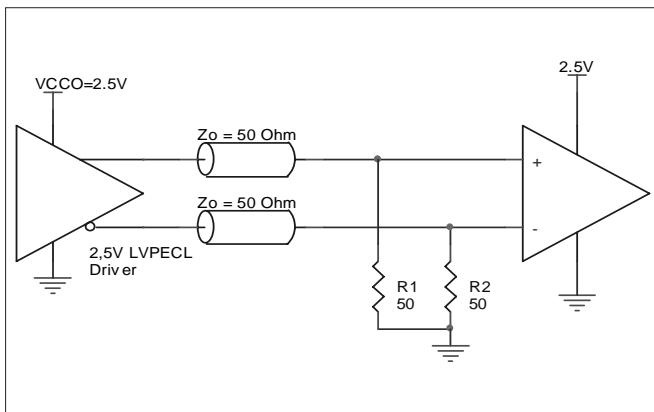
ground level. The R3 in Figure 5B can be eliminated and the termination is shown in Figure 5C.



**FIGURE 5A. 2.5V LVPECL DRIVER TERMINATION EXAMPLE**



**FIGURE 5B. 2.5V LVPECL DRIVER TERMINATION EXAMPLE**



**FIGURE 5C. 2.5V LVPECL TERMINATION EXAMPLE**



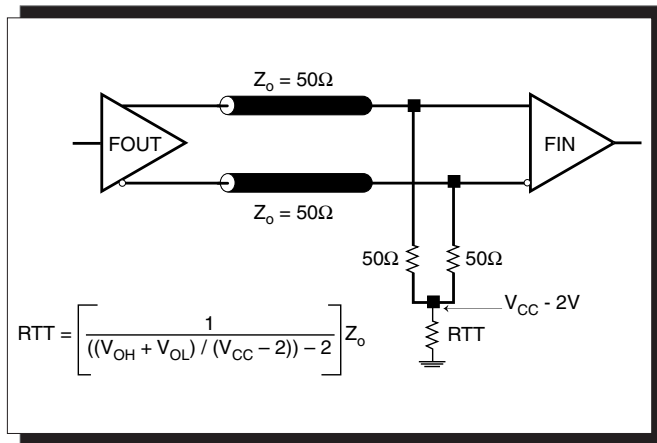


**TERMINATION FOR 3.3V LVPECL OUTPUT**

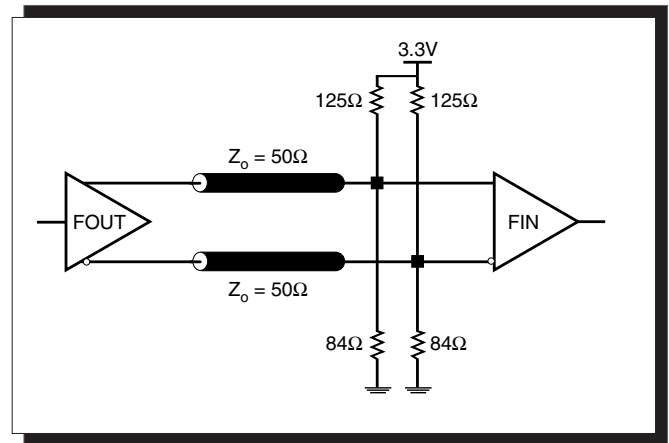
The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUTx and nFOUTx are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to

drive 50Ω transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 6A and 6B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.



**FIGURE 6A. LVPECL OUTPUT TERMINATION**

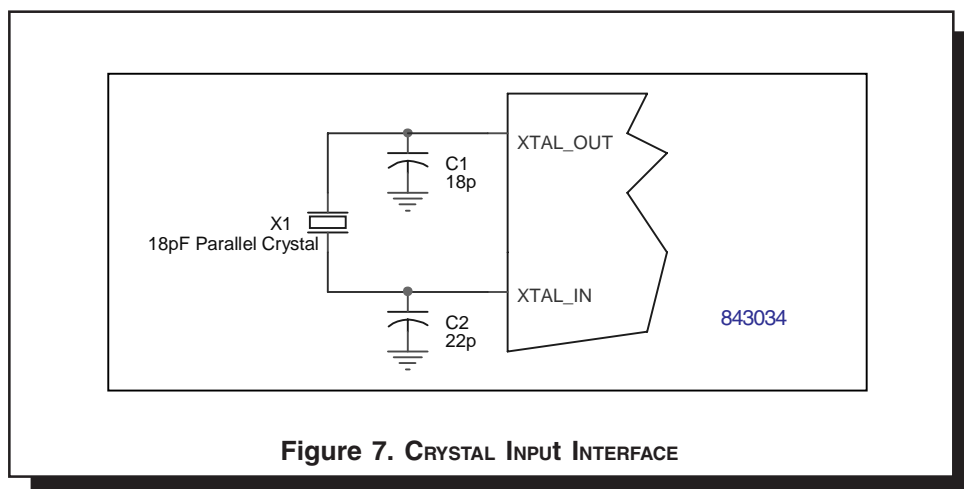


**FIGURE 6B. LVPECL OUTPUT TERMINATION**

**CRYSTAL INPUT INTERFACE**

The ICS843034 has been characterized with 18pF parallel resonant crystals. The capacitor values, C1 and C2, shown in *Figure 7* below were determined using a 25MHz, 18pF parallel resonant crystal and

were chosen to minimize the ppm error. The optimum C1 and C2 values can be slightly adjusted for different board layouts.



**Figure 7. CRYSTAL INPUT INTERFACE**



## POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the ICS843034. Equations and example calculations are also provided.

### 1. Power Dissipation.

The total power dissipation for the ICS843034 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for  $V_{CC} = 3.3V + 5\% = 3.465V$ , which gives worst case results.

**NOTE:** Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)<sub>MAX</sub> =  $V_{CC\_MAX} * I_{EE\_MAX} = 3.465V * 185mA = 641mW$
- Power (outputs)<sub>MAX</sub> = **30mW/Loaded Output pair**  
If all outputs are loaded, the total power is  $2 * 30mW = 60mW$

**Total Power**<sub>MAX</sub> (3.465V, with all outputs switching) =  $641mW + 60mW = 701mW$

### 2. Junction Temperature.

Junction temperature,  $T_j$ , is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for  $T_j$  is as follows:  $T_j = \theta_{JA} * Pd\_total + T_A$

$T_j$  = Junction Temperature

$\theta_{JA}$  = Junction-to-Ambient Thermal Resistance

$Pd\_total$  = Total Device Power Dissipation (example calculation is in section 1 above)

$T_A$  = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance  $\theta_{JA}$  must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 42.1°C/W per Table 8 below.

Therefore,  $T_j$  for an ambient temperature of 70°C with all outputs switching is:

$70^\circ C + 0.701W * 42.1^\circ C/W = 99.5^\circ C$ . This is well below the limit of 125°C.

This calculation is only an example.  $T_j$  will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

**TABLE 8. THERMAL RESISTANCE  $\theta_{JA}$  FOR 48-PIN LQFP, FORCED CONVECTION**

$\theta_{JA}$ by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

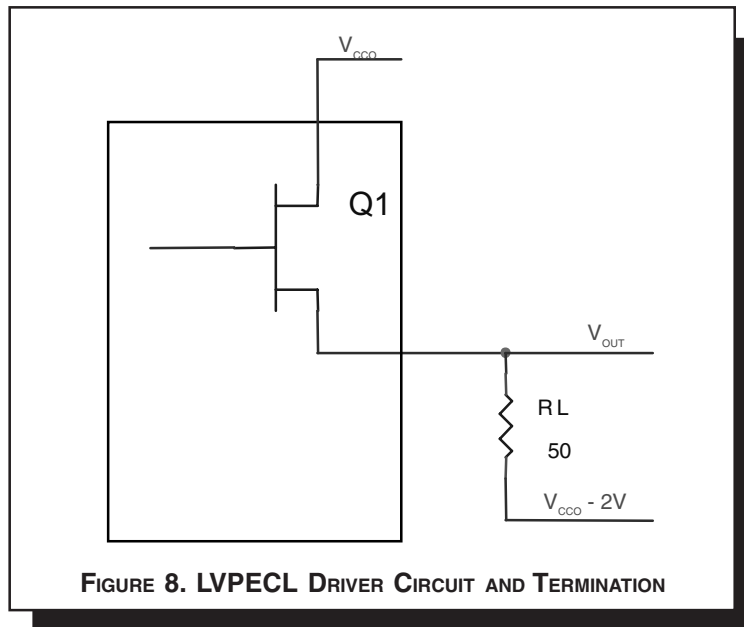
**NOTE:** Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.



3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in Figure 8.



**FIGURE 8. LVPECL DRIVER CIRCUIT AND TERMINATION**

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of  $V_{CCO} - 2V$ .

- For logic high,  $V_{OUT} = V_{OH\_MAX} = V_{CCO\_MAX} - 0.9V$

$$(V_{CCO\_MAX} - V_{OH\_MAX}) = 0.9V$$

- For logic low,  $V_{OUT} = V_{OL\_MAX} = V_{CCO\_MAX} - 1.7V$

$$(V_{CCO\_MAX} - V_{OL\_MAX}) = 1.7V$$

Pd\_H is power dissipation when the output drives high.

Pd\_L is the power dissipation when the output drives low.

$$Pd_H = [(V_{OH\_MAX} - (V_{CCO\_MAX} - 2V))/R_L] * (V_{CCO\_MAX} - V_{OH\_MAX}) = [(2V - (V_{CCO\_MAX} - V_{OH\_MAX}))/R_L] * (V_{CCO\_MAX} - V_{OH\_MAX}) = [(2V - 0.9V)/50\Omega] * 0.9V = 19.8mW$$

$$Pd_L = [(V_{OL\_MAX} - (V_{CCO\_MAX} - 2V))/R_L] * (V_{CCO\_MAX} - V_{OL\_MAX}) = [(2V - (V_{CCO\_MAX} - V_{OL\_MAX}))/R_L] * (V_{CCO\_MAX} - V_{OL\_MAX}) = [(2V - 1.7V)/50\Omega] * 1.7V = 10.2mW$$

Total Power Dissipation per output pair = Pd\_H + Pd\_L = 30mW



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MULTI-RATE 3.3V, 2.5V LVPECL FREQUENCY SYNTHESIZER

**RELIABILITY INFORMATION**

**TABLE 9.  $\theta_{JA}$  VS. AIR FLOW TABLE FOR 48 LEAD LQFP**

<b><math>\theta_{JA}</math> by Velocity (Linear Feet per Minute)</b>			
	<b>0</b>	<b>200</b>	<b>500</b>
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

**NOTE:** Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

**TRANSISTOR COUNT**

The transistor count for ICS843034 is: 11,748



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PACKAGE OUTLINE - Y SUFFIX FOR 48 LEAD LQFP

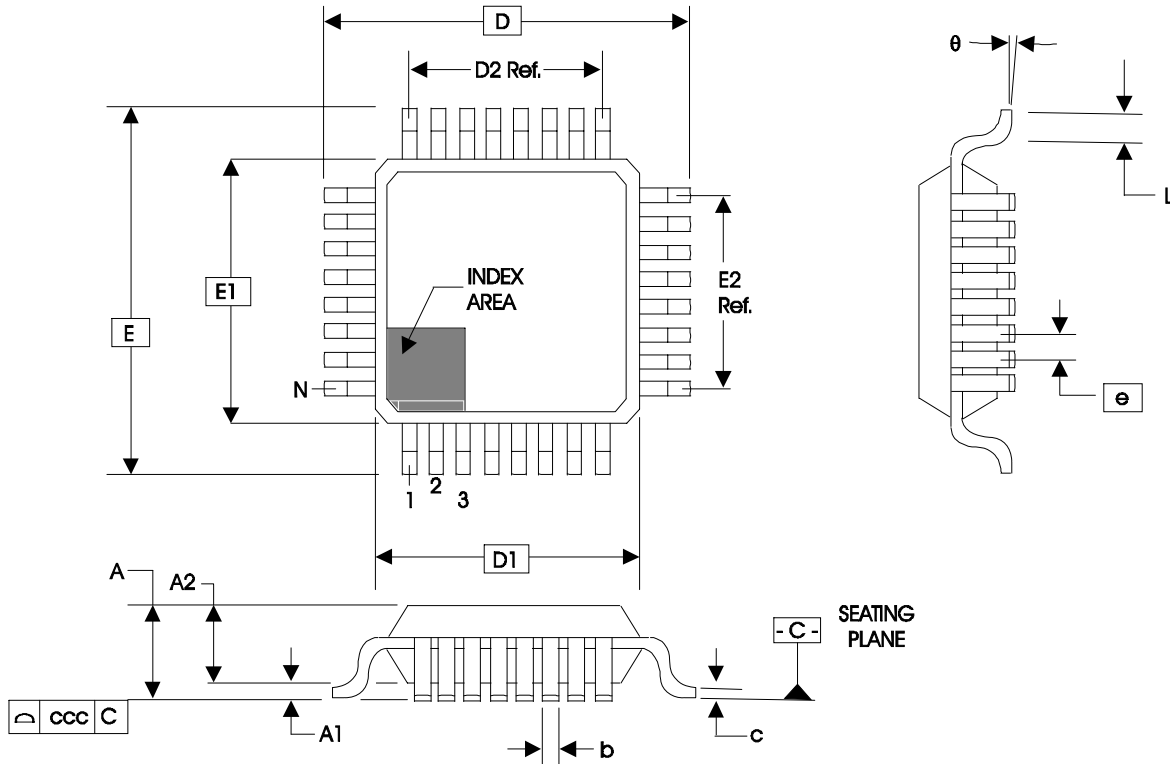


TABLE 10. PACKAGE DIMENSIONS

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS			
SYMBOL	BBC		
	MINIMUM	NOMINAL	MAXIMUM
N	48		
A	--	--	1.60
A1	0.05	--	0.15
A2	1.35	1.40	1.45
b	0.17	0.22	0.27
c	0.09	--	0.20
D	9.00 BASIC		
D1	7.00 BASIC		
D2	5.50 Ref.		
E	9.00 BASIC		
E1	7.00 BASIC		
E2	5.50 Ref.		
e	0.50 BASIC		
L	0.45	0.60	0.75
θ	0°	--	7°
ccc	--	--	0.08

Reference Document: JEDEC Publication 95, MS-026



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**TABLE 11. ORDERING INFORMATION**

<b>Part/Order Number</b>	<b>Marking</b>	<b>Package</b>	<b>Shipping Packaging</b>	<b>Temperature</b>
ICS843034AY	ICS843034AY	48 Lead LQFP	tray	0°C to 70°C
ICS843034AYT	ICS843034AY	48 Lead LQFP	1000 tape & reel	0°C to 70°C

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